



## MRSI is Sponsoring IMAPS 2017 — Raleigh IMAPS 50th Anniversary Symposium



- Exhibition October 10-11, 2017
- Raleigh, NC
- Booth #234

[Schedule a Meeting](#)

The 50th Annual International Symposium on Microelectronics will be held from October 9-12, 2017 in Raleigh, North Carolina. MRSI Systems will be exhibiting - Booth #234. There will be over 120 booths on the showroom floor from October 10-11, 2017, with companies from all segments of the microelectronics industry including Military, Aerospace, Computing, Automotive, and Industrial. Learn more about [IMAPS Raleigh 2017](#).

### MRSI Systems Sponsorship

MRSI Systems has been a member and supporter of IMAPS for more than 30 years and is pleased to sponsor the exhibit lunch at the 2017 IMAPS Symposium. Please visit the MRSI Systems' Booth (#234) to learn about our new die bonder for high volume manufacturing. [Schedule a meeting](#) with MRSI Systems at IMAPS Raleigh to learn more about MRSI's die bonders and epoxy dispensers. MRSI Systems has been serving optoelectronic and microelectronic customers for the past thirty-three years and understands their requirement to scale efficiently in today's fast-paced marketplace. Contact MRSI Systems to learn how MRSI can help your company scale.

## Visit MRSI Systems at Productronica 2017 in Germany

Visit us!  
Hall B2, Stand 401



productronica 2017

November 14–17, 2017, Messe München

## CIOE - Big Success with Introduction of MRSI-HVM3



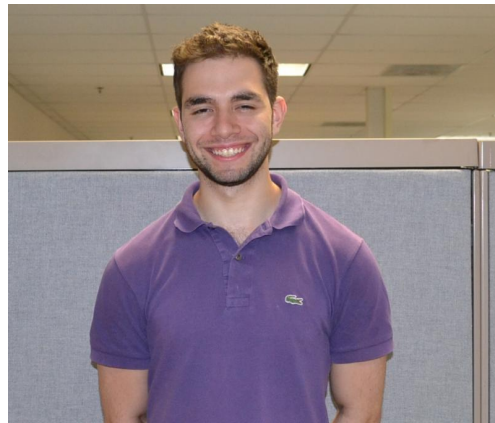
Thanks to our loyal customers and our Chinese representative CYCAD for making the China International Optoelectronic Exposition at Shenzhen Conference & Exhibition Center such a major success. MRSI Systems introduced the MRSI-HVM3, 3 micron die bonder for high volume manufacturing of photonic, sensor, and semiconductor devices. The system delivers industry leading speed without sacrificing high precision and superior flexibility by incorporating MRSI's latest hardware and software innovations. Once again the show machine is heading directly to a customer site to fill an order!

## MRSI Team is Expanding



### Nathan Fall

Please welcome Nathan to the Applications Engineering team. He has experience with die bonders, SMT rework, and CNC milling machines and will support all of our machines. Nathan has many years of experience in the electronics field and graduated from Excelsior College in Albany, NY.



### Daniel Caraballo

Joining MRSI in the position of Controls Engineer Daniel will be working closely with key folks in engineering, learning about our machine control systems and advancing our technology in this area. Daniel graduated from Wentworth Institute of Technology with a Bachelor of Science degree in Electrical Engineering and a minor in Applied Mathematics.

## MRSI Blog - Don't Miss Our Regular Weekly Insights into the Advanced Electronic Packaging Industry

- [Epoxy Deposition – Requirement for High-Volume Manufacturing \(HVM\) of Chip-on-Submount \(CoS\)](#)
- [Case Study – Leading Photonic Component Manufacturer Selects MRSI Systems to Produce Photonic Components Faster](#)
- [Automated Die Bonding for High Volume Optoelectronics Packaging](#)

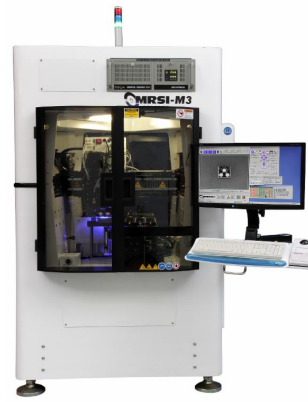
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**NEW PRODUCT**  
**MRSI-HVM3**  
**3-MICRON DIE BONDER**



**MRSI-705**  
**5-MICRON DIE BONDER**



**MRSI-M3**  
**3-MICRON DIE BONDER**



**MRSI-175Ag**  
**EPOXY DISPENSER**



**MRSI-M1**  
**1-MICRON DIE BONDER**

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